

产品承认书

SPECIFICATION FOR APPROVAL

CUSTOMER:

CUSTOMER P/N:

CD.com P/N.:

C221480300

DESCRIPTION:

Common Mode Choke

REF NO:

T22*14*8-3MH

REV/NO:

A/0

DATE:

2021-4-22

ATTACHMENT:

■ SPECIFICATION

■ SAMPLE Q'TY OF SAMPLES _____ PCS

	√	CUSTOMER'S SIGNATURE	REMARK
FULL APPROVED			
CONDITIONAL APPROVED			
REJECTED			



深圳磁联达电子有限公司

Shenzhen magnetic Lianda Electronics Co. Ltd.

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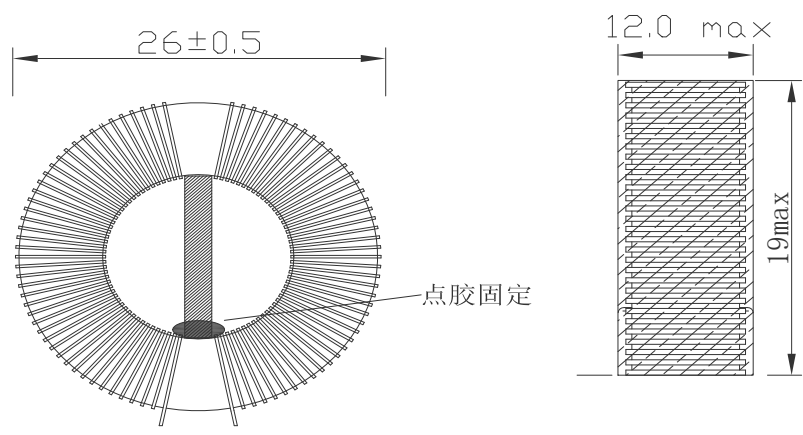
Email: cd001@cd-tek.com

Http: //www.cd-tek.com

RoHS
Compliant

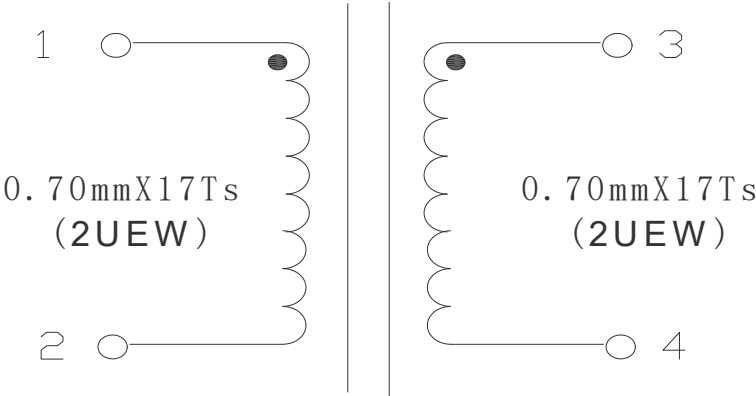


1. DIMENSIONS & MARKING:



- 1.1 分开绕线，中间用隔板分开，点胶固定；
- 1.2 产品为卧式.

2. SCHEMATICS:



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3. WINDING SPEC:

端子Terminal	线规 Wire Gauge	圈数 Turns	备注 Remark
1-2	2UEW 0.70mm 180℃	17Ts	单线分绕
3-4	2UEW 0.70mm 180℃	17Ts	单线分绕

4.ELECTRICAL SPECIFICATIONS @25℃

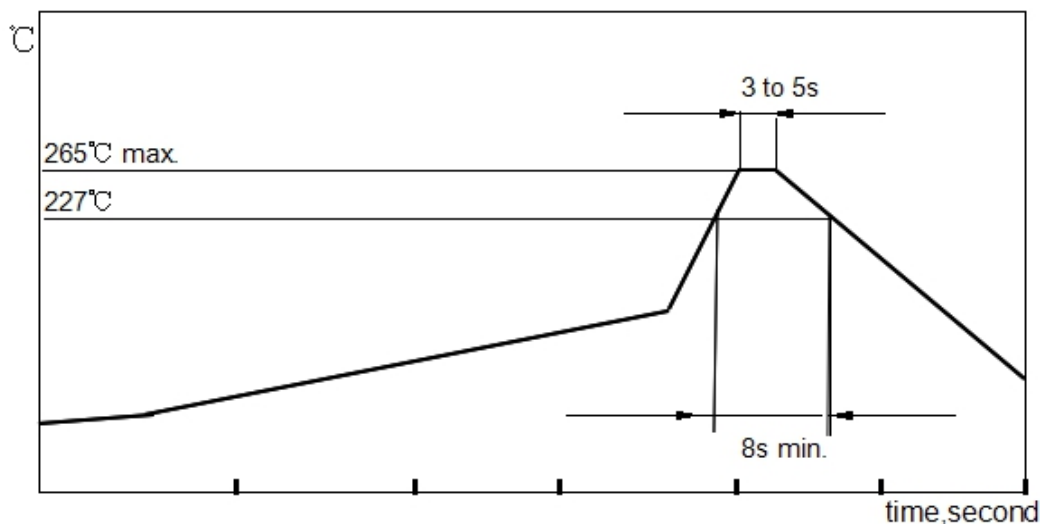
- 4.1 Inductance: (1-2) = (3-4) = 3mH MIN @ 10KHz 0.25V;
4.2 Turns Ratio: (1-2) : (3-4) = 1:1±3% @10KHz, 0.1Vac;
4.3 DCR: (1-2) = 0.60Ω MAX (3-4) = 0.60Ω MAX;
4.4 ΔL: L(1-2)-L(3-4) @1KHz, 1V ≤ 1%
4.5 Rated Current: ΔT≤45℃ 4.5A
4.6 Hi-Pot: 1mA/2S/60Hz (Vac) : (1-2) TO (3-4) 600V
4.7 Insulation Resistance: DC100V ≥100MΩ MIN.

5.MATERIALLIST

Item	Material	Partnumber/supplier	UL file
Core	T22*14*8	TIANCI,ELECTRONIC	
Copper wire	2UEW 0.70mm 180℃	SHING SHUN	
Stannum	Sn99.3-Cu0.7	YUNXI	
VARNISH	G-8500A/B	EATTO	

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6. Recommended Lead Free IR Reflow Soldering Curve:



Item	Solder technique simulation	Temperature (°C)	Time(s)	Temperature ramp/immersion and emersion rate
1	Solder iron	350±10 (solder iron temp)	4~5	
2	Vapor phase reflow	215±5 (vapor temp)	10±1	25mm/s±6mm/s
3	Wave:Topside Board-mount product	260±5 (solder temp)	20±1	
4	Wave:Bottomside Board-mount	260±5 (solder temp)	10±1	Preheat 1°C/s~4°C/s to within 100°C of solder temp 25mm/s±6mm/s
5	Vapor phase reflow	215±5 (vapor temp)	215±5 (vapor temp)	

6.1 Terminal strength: Pull test withstand 9.8N 60+/-0.5S no looseness or movement.

6.2 Solderbility: Dipped in 245°C+/-5°C molten solder for 3+/-0.5 seconds,95% min shall be smooth any and bright.

6.3 Resistance to soldering heat : Dip in 260°C+/- 5°C molten solder for 5+/- 0.5 seconds. Shall not be any abnormality.

6.4 Vibration: 1.5mm amplitude total excursion 10-55-10 Hz traversed in 1minute, x,y,z, axis for 2 hours. Shall not be any abnormality.

6.5 Random drop (Packing condition): Height 60cm, 3 times on the wood floorboard ,shall not be any abnormality.

6.6 Dry heat: 100+/-2°C 96 hours.

6.7 Cold: -20+/-2°C 96 hours.

6.8 Damp Heat: 60+/-2°C, 93+/-3% RH 96 hours.

6.9 Change of temperature: exposed 5 cycle; each consisting of 30 minutes at -20+/-2°C,2-3minutes at 20+/-2°C,30 minutes at 85+/-2°C, 2-3 minutes at 20+/-2°C.

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